

Excellent Integrated System Limited

Stocking Distributor

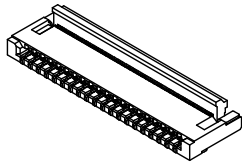
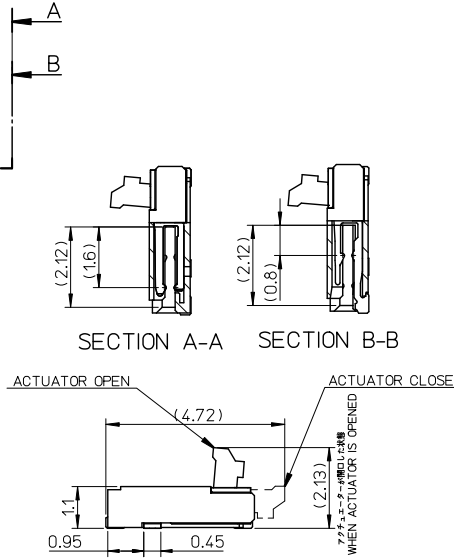
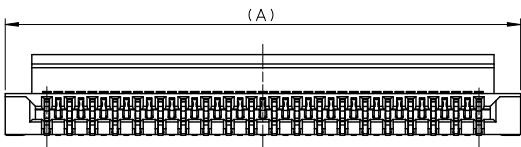
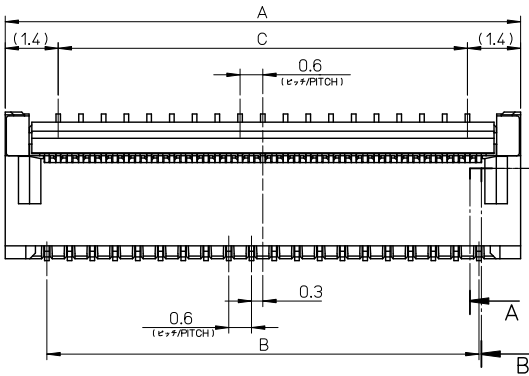
Click to view price, real time Inventory, Delivery & Lifecycle Information:

[Molex Connector Corporation](#)
[5023503300](#)

For any questions, you can email us directly:

sales@integrated-circuit.com

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斜視図
SCALE 5:1

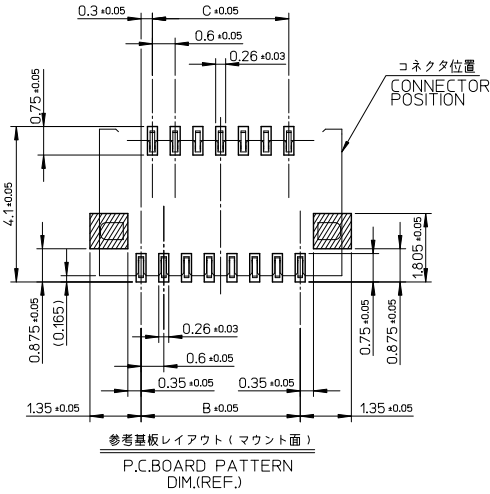
部品構成
PART COMPOSITION

- ハウジング: 液晶ポリマー(LCP),
ガラス充填, UL94 V-0, ナチュラル(白)
HOUSING: LIQUID CRYSTAL POLYMER (LCP),
GLASS FILLED, UL94 V-0, NATURAL (WHITE)
- 奇数ターミナル: 銅合金
ODD TERMINAL: COPPER ALLOY
処理: ニッケル下地 部分金メッキ ニッケルストライプ(バリア)
FINISH : PARTLY GOLD
OVER NICKEL PLATING
NI STRIPE(BARRIER)
- 偶数ターミナル: 銅合金
EVEN TERMINAL: COPPER ALLOY
処理: ニッケル下地 部分金メッキ ニッケルストライプ(バリア)
FINISH : PARTLY GOLD
OVER NICKEL PLATING
NI STRIPE(BARRIER)
- アクチュエータ: ポリアミド(PA) 黒色 UL94V-0
ACTUATOR MATERIAL :POLYAMIDE(PA) BLACK UL94-V0
- ネイル: 銅青銅
NAIL MATERIAL: PHOSPHOR BRONZE
処理: ニッケル下地 部分金メッキ
FINISH : TIN OVER NICKEL PLATING
- ELV及RoHS適合品
ELV & RoHS COMPLIANT

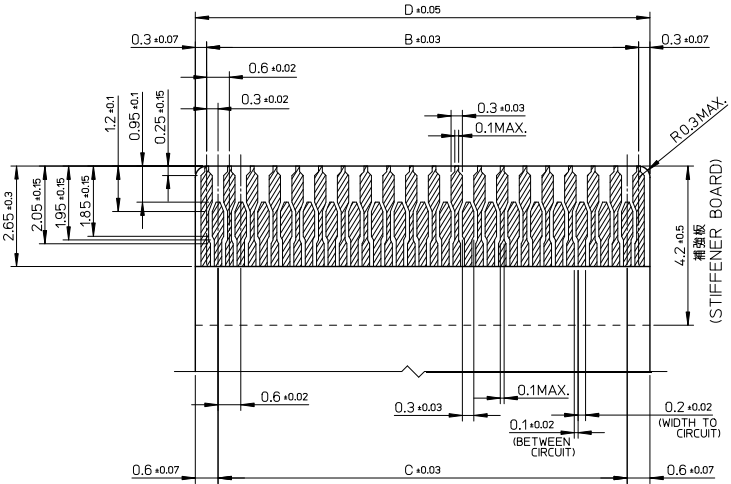
15.6	14.4	15	17.2	502350-5100	51
14.4	13.2	13.8	16.0	502350-4700	47
13.8	12.6	13.2	15.4	502350-4500	45
12.6	11.4	12	14.2	502350-4100	41
12	10.8	11.4	13.6	502350-3900	39
11.4	10.2	10.8	13	502350-3700	37
10.2	9	9.6	11.8	502350-3300	33
9.6	8.4	9	11.2	502350-3100	31
7.2	6	6.6	8.8	502350-2300	23
6	4.8	5.4	7.6	502350-1900	19
4.8	3.6	4.2	6.4	502350-1500	15
D	C	B	A	EMBOSSED PACKAGE	極数
				オーダー番号 ORDER NO.	CIRCUITS

REVISED EC NO. J2011-0598 DRAWN: SHIRATA 2010/10/19 CHKD: TAKAHASHI 2010/10/19 APPR: MORIKAWA 2010/10/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
			MM ONLY	10:1	METRIC	
	10 UNDER	± 0.2	DRAWN BY	DATE	TITLE	
	10 OVER 30 UNDER	± 0.25	T. HIRAYAMA	2009/01/05	0.3 FPC CONN. E/O H=1.1 HOUSING ASSY WITH GUIDE	
30 OVER	± 0.3	CHECKED BY	DATE	MOLEX INCORPORATED		
ANGULAR	± 3 °	N. MATSUURA	2009/01/05	MATERIAL NO.		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY	DATE	DOCUMENT NO.		
		KMORI KAWA	2010/10/25	SD-502350-001		
		SEE CHART		SHEET NO.		
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		1 OF 2		

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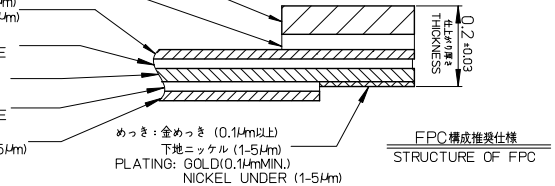


参考基板レイアウト (マウント面)
P.C. BOARD PATTERN DIM.(REF.)
推奨メタルマスク厚さ : 0.1mm
RECOMMENDED METAL MASK THICKNESS : 0.1mm
推奨開口率 : 100%
APERTURE RATE : 100%



適合FPC推奨寸法
仕上がり厚さ : 0.2±0.03
APPLY FPC RECOMMENDED DIM. THICKNESS : 0.2±0.03

補強板: ポリイミド
REINFORCE BOARD: POLYIMIDE
熱硬化接着剤
THERMOSETTING ADHESIVE
ベースフィルム: ポリイミド (25μm)
BASE FILM: POLYIMIDE(25μm)
熱硬化接着剤
THERMOSETTING ADHESIVE
導体部: 銅箔 (35μm)
COPPER FOIL (35μm)
熱硬化接着剤
THERMOSETTING ADHESIVE
カバーレイ: ポリイミド (25μm)
COVER FILM: POLYIMIDE(25μm)

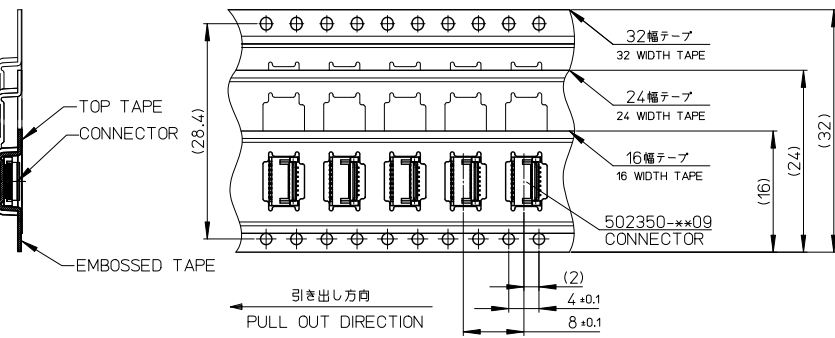
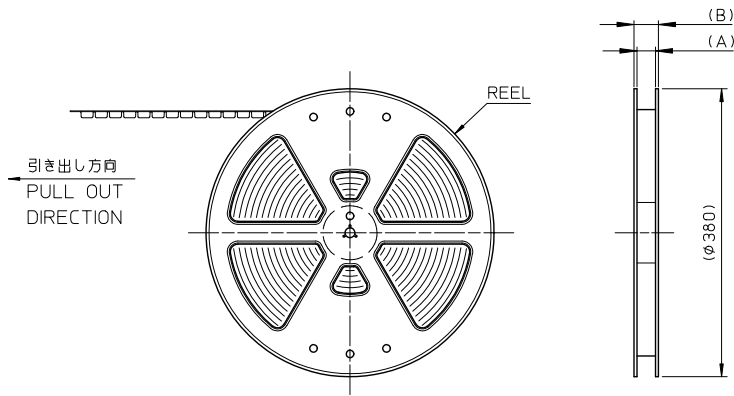


注記
NOTE

- 基板実装前にアクチュエータを操作しないで下さい。
PLEASE DO NOT OPERATE THE ACTUATOR BEFORE MOUNTING.
 - 必ず基板に実装してからアクチュエータを操作して下さい。
PLEASE OPERATE THE ACTUATOR AFTER MOUNTING ON THE SUBSTRATE.
 - FPCについて
ABOUT FPC
補強フィルム材質はポリイミドを推奨します。ベースフィルムは25μmを推奨します。
接着剤は熱硬化接着剤を推奨します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。
RECOMMENDED STIFFENER MATERIAL: POLYIMIDE
RECOMMENDED BASE FILM THICKNESS: 25 MICROMETER
RECOMMENDED ADHESIVE: THERMOSETTING ADHESIVE
NOTE: PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.
 - 打抜き方向は導体側から補強板側を推奨致します。
導体部については軟銅箔35μmまたは450μmを推奨致します。
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
RECOMMENDED CONDUCTOR SPECIFICATION:
THICKNESS OF SOFT COPPER FOIL: 35MICROMETER OR 50 MICROMETER
4. 平坦度は0.1以下
COPLANARITY TO BE 0.1 MAXIMUM

REVISED EC NO. J2011-0598 DRAWN: SHIRATA 2010/10/19 CHK: KAKIHASHI 2010/10/19 APPR: MORIKAWA 2010/10/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY T. HIRAYAMA	DATE 2009/01/05	TITLE 0.3 FPC CONN. E/O H=1.1 HOUSING ASSY WITH GUIDE	
	10 OVER 30 UNDER	± 0.25	CHECKED BY N. MATSUURA	DATE 2009/01/05	MOLEX INCORPORATED	
	30 OVER	± 0.3	APPROVED BY KMORI KAWA	DATE 2010/10/25	DOCUMENT NO. SD-502350-001	SHEET NO. 2 OF 2
	ANGULAR	± 3 °	MATERIAL NO. SEE CHART1	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
	DRAFT WHERE APPLICABLE WITHIN DIMENSIONS		SIZE A3			

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エンボステープ内の製品の向き
DIRECTION OF CONNECTOR IN
EMBOSSSED TAPE

NOTES

- 製品 (502350-xx09) の詳細寸法については、図面 SD-502350-001をご参照下さい。
IN THE PACKAGE, PART NO. 502350-xx09 DETAILED DIMENSIONS. REFER TO SALES DRAWING NO. SD-502350-001.
- 梱包数量 : 3000 個/リール
NUMBER OF CONNECTORS : 3000 PCS/REEL
- リードテープ長さ
LEAD TAPE LENGTH

トップテープ接着部
TOP TAPE BONDED PART
(空きエンボス)
(EMPTY)

トップテープ
リーダー部
TOP TAPE LEADER PART
400 MIN.

部品挿入部
COMPONENT
SUPPLIER

未接着部 (空部)
TAL PART
(EMPTY)
160 MIN.
- 材料
キャリアテープ : ポリスチレン (PS)
トップテープ : PET, OTHER
リール : ポリスチレン (PS) <リサイクル材を含む>
MATERIAL
CARRIER TAPE : POLYSTYRENE(PS)
TOP TAPE : PET, OTHER
REEL : POLYSTYRENE(PS)
<RECYCLE MATERIAL CONTAINED>
- ELV及びRoHS適合品
ELV AND RoHS COMPLIANT
- トップテープの剥離強度については、IEC60286-3に準拠
Top tape peel force is defined by IEC60286-3.

37.4	33.4	32	502350-5100	51
			502350-4700	47
			502350-4500	45
			502350-4100	41
			502350-3900	39
			502350-3700	37
			502350-3300	33
			502350-3100	31
			502350-2300	23
			502350-1900	19
29.4	25.4	24	502350-1500	15
21.4	17.4	16		
B	A	WIDTH TAPE	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	CIRCUIT

REVISED EC NO. J2011-0598 DRAWN: SHIRATA 2010/10/19 CHKD: TAKAHASHI 2010/10/19 APPR: MORIKAWA 2010/10/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	MODEL NO.	
	10 UNDER	± 0.2	DRAWN BY DATE T. HIRAYAMA 2009/01/05		TITLE 0.3 FPC CONN. H=1.1 EMBSTP PKG			
	10 OVER 30 UNDER	± 0.25	CHECKED BY DATE N. MATSUURA 2009/01/05		MATERIAL NO. SEE CHART			
	30 OVER	± 0.3	APPROVED BY DATE KMORIKAWA 2010/10/25		DOCUMENT NO. SD-502350-002			
	ANGULAR	± 3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SHEET NO. 1 OF 1		MATERIAL NO. SD-502350-002	

9 8 7 6 5 4 3 2 1 EN-02JA(021)